

BRCM24C08SC

EUF P 57F3;VF VRS0; ; NeIw L³F

41: Y	5.8£8.8Y	4 P k}	41: £5.8Y
733Nk}			

HBM mode Pinning

Slq	Qd p h	W sh	Ghvfulswlr q
4	QF	0	
5	QF	0	
6	H5	lqsxw	
7	JQG	Jurxqg	
8	VGD	L2R	M

/ Marking

			3⁄8
			3⁄8

/ Reliability Characteristic

		Ñ				

BRCM24C08SC



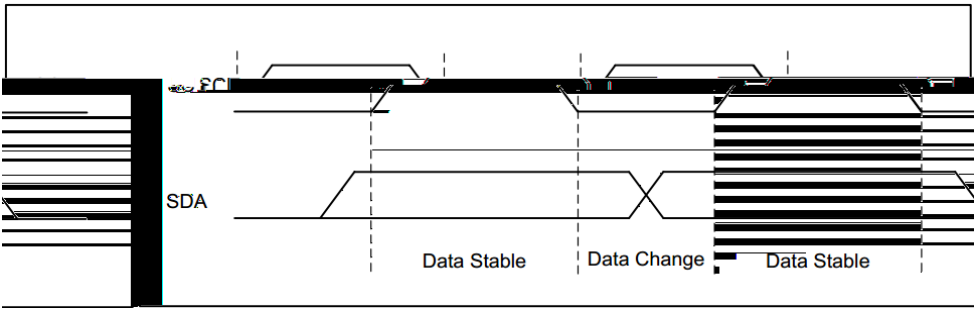
DATA SHEET

		□			□ □			

/ Functional Description

H / Data Input

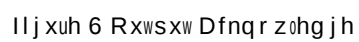
VGD VGD VF0 + 4 , VF0
VGD + 4 ,



I2C xuh 4 Gdwd Ydolgwl

H / Start Condition

/ Functional Description



H / Standby Mode

EUF P 57F3;VF =d, /+e,
/f,

H / Soft Reset

7

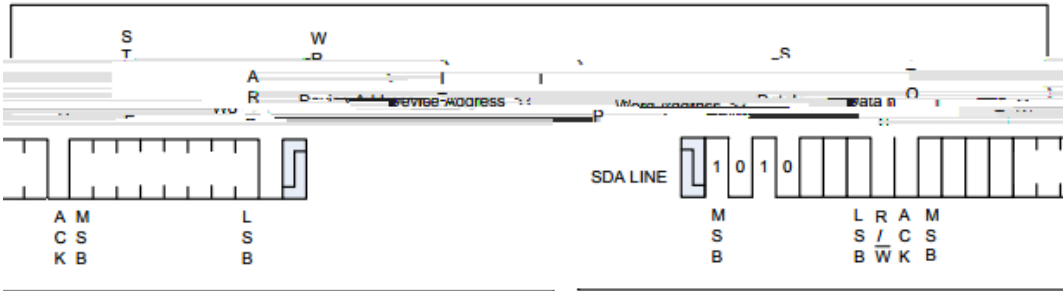


H / Device Addressing

EUF P 57F3;VF ; 4

/ Functional Description

/ Functional Description

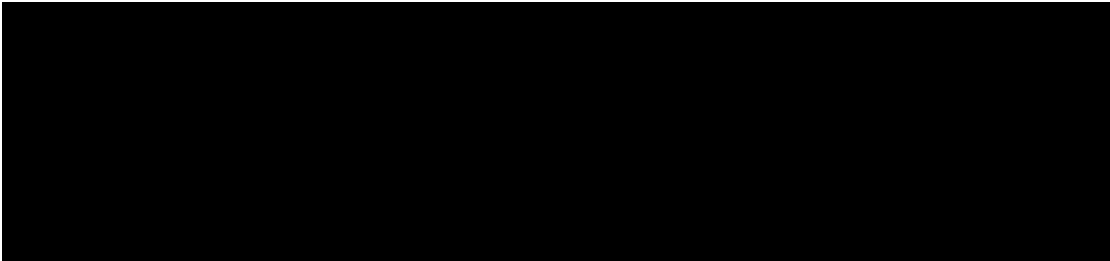


H / Page Write

EUF P 57F3;VF

„ 3 †

EUF P 57F3;VF



/ Functional Description

H / Acknowledge Polling

EUFP 57F3;VF
2 EUFP 57F3;VF
„ 3 †

H / Write Identification Page

49
+d, 4344e
+e, D8 2 D7 3 4 D: 2 D9 „ 33 †
+f, D6 2 D3
QrDFN

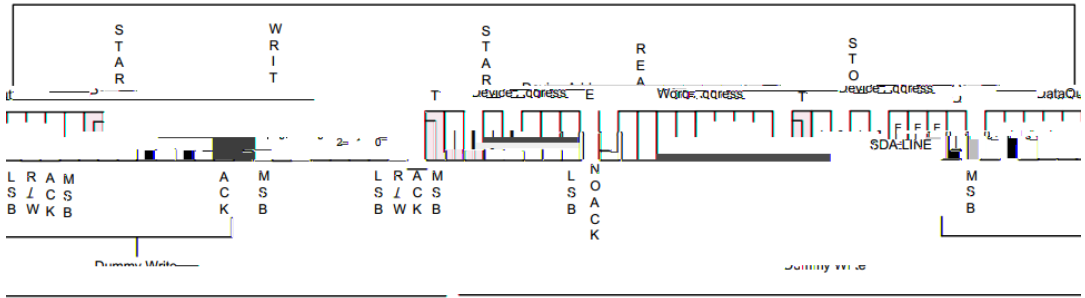
H / Lock Identification Page

LG Or fn LG
+d, 4344e>
+e, D9 4 >
+f, {{{ {{4{ { 3 4

/ Functional Description

H	/ Read Operations		
2		2	„ 4 †
	>		
H			

/ Functional Description



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/ Functional Description

H / Read Identification Page

49

4344e	D: 2 D9	3	D8	D7 2 D3	LG
			43g		9 LG

/ Functional Description

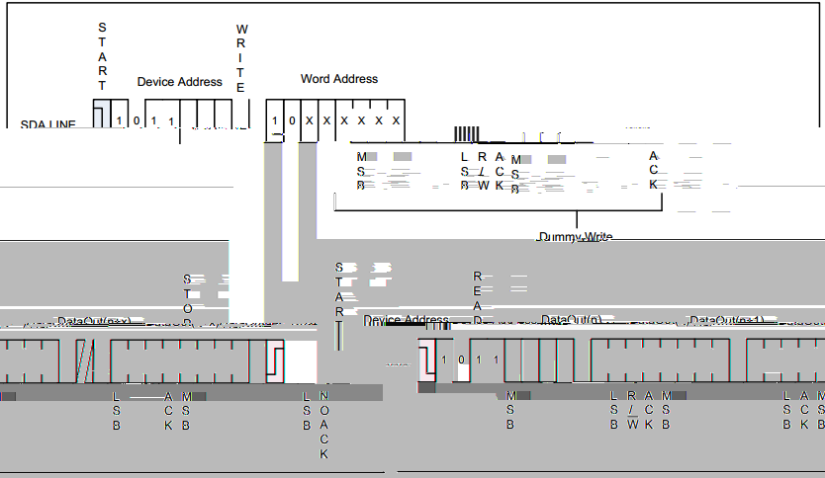
D: D9 „ 43 † 5 „ 43 †

;3k

45; 49

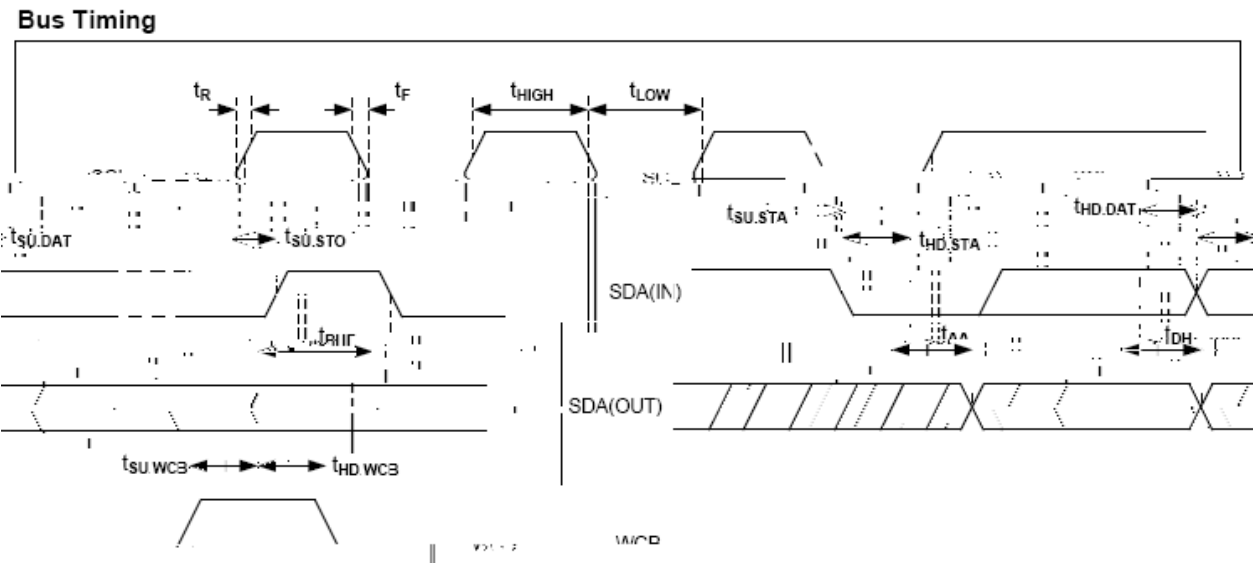
45; DFN

:

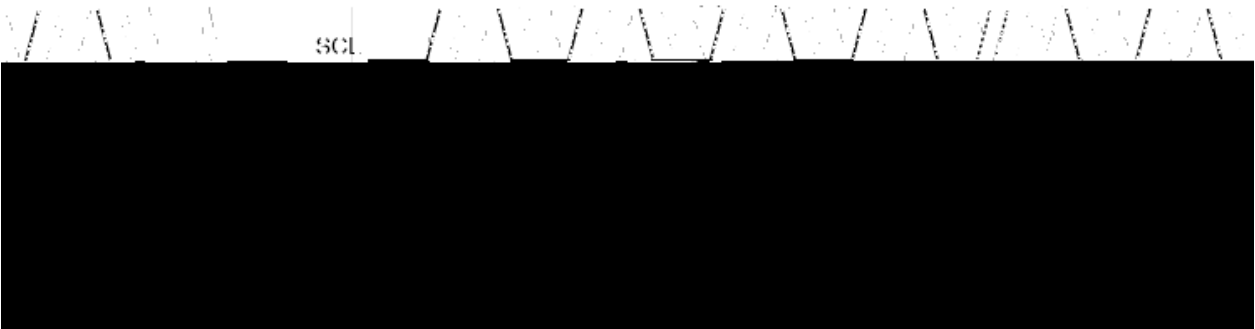


Il j xuh 44 Vh t xhqwldo Uhdg

/ Time Sequence Diagram

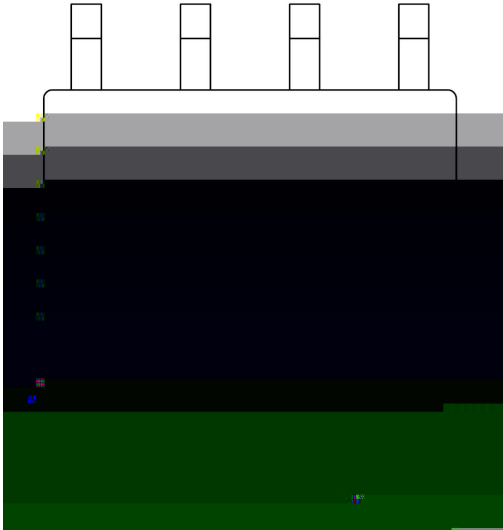


Write Cycle Timing



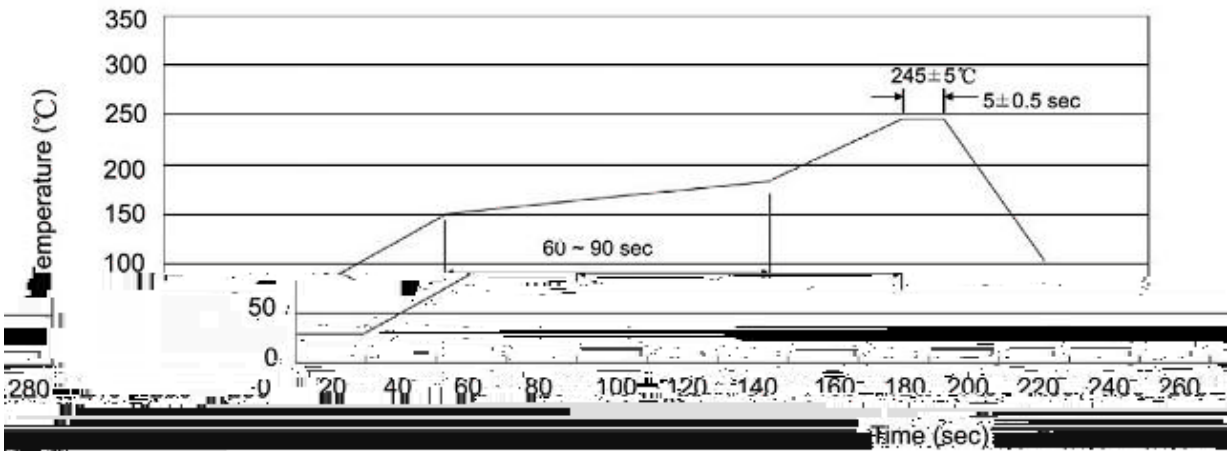
This architectural section drawing illustrates a cross-section of a building. The drawing shows a large open space on the left, a central corridor, and a series of rooms on the right. The drawing is labeled with 'R' and 'N' at the bottom right, indicating orientation or section type.

/ Marking Instructions



57F3;

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



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/ Resistance to Soldering Heat Test Conditions

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